



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**Notification# 20260428000.0
Datasheet for LOG114, INA146, INAx126, and INA122
Information Only**

Date: April 28, 2026
To: PREMIER FARNELL PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the Change Management team.

Sincerely,

Change Management Team
SC Business Services

20260428000.0
Information Only Datasheet
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LOG114AIRGVT	NULL
INA126UA	NULL

Technical details of this Product Change follow on the next page(s).

Notification Number:	20260428000.0	Notification Date:	April 28, 2026
Title:	Datasheet for LOG114, INA146, INAx126, and INA122		
Customer Contact:	Change Management team	Dept:	Quality Services
Change Type:	Electrical Specification		

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



LOG114
SBOS301C – MAY 2004 – REVISED DECEMBER 2025

Changes from Revision B (March 2025) to Revision C (December 2025)	Page
• Added description of device flow information in the <i>Specifications</i>	4
• Added <i>all chips site origins</i> (CSO) condition to the typical test conditions in the <i>Electrical characteristics</i>	6
• Added different fabrication process specifications for Gain Bandwidth in the <i>Electrical Characteristics</i>	6
• Added different fabrication process specifications for Slew Rate in the <i>Electrical Characteristics</i>	6
• Added different fabrication process specifications for Short-Circuit Current in the <i>Electrical Characteristics</i> ...	6
• Added different fabrication process specifications for Step Response 8nA to 240nA (Decreasing) Current in the <i>Electrical Characteristics</i>	6
• Changed Step Response 8nA to 240nA (Decreasing) from 6μs to 7.6μs in the <i>Electrical Characteristics</i>	6
• Added different fabrication process specifications for Step Response 10nA to 100nA (Decreasing) Current in the <i>Electrical Characteristics</i>	6
• Added different fabrication process specifications for Step Response 10nA to 1μA (Decreasing) Current in the <i>Electrical Characteristics</i>	6
• Added different fabrication process specifications for Quiescent Current in the <i>Electrical Characteristics</i>	6
• Added <i>all chips site origins</i> (CSO) condition to the typical test conditions in the <i>Electrical characteristics</i>	8
• Added different fabrication process specifications for Gain Bandwidth in the <i>Electrical Characteristics</i>	8
• Added different fabrication process specifications for Slew Rate in the <i>Electrical Characteristics</i>	8
• Added different fabrication process specifications for Short-Circuit Current in the <i>Electrical Characteristics</i> ...	8
• Added different fabrication process specifications for Step Response 8nA to 240nA (Decreasing) Current in the <i>Electrical Characteristics</i>	8
• Changed Step Response 8nA to 240nA (Decreasing) from 6μs to 7.6μs in the <i>Electrical Characteristics</i>	8
• Added different fabrication process specifications for Step Response 10nA to 100nA (Decreasing) Current in the <i>Electrical Characteristics</i>	8
• Added different fabrication process specifications for Step Response 10nA to 1μA (Decreasing) Current in the <i>Electrical Characteristics</i>	8
• Added different fabrication process specifications for Quiescent Current in the <i>Electrical Characteristics</i>	8
• Added <i>all chips site origins</i> (CSO) condition to the typical test conditions in the <i>Typical Characteristics</i>	10
• Added <i>A₄ and A₅ Gain and Phase vs Frequency, A₄ and A₅ Noninverting Closed-Loop Response, A₄ and A₅ Inverting Closed-Loop Response, A₄ and A₅ Capacitive Load Response</i> curves for CSO: SHE flow in the <i>Typical Characteristics</i>	10
• Added CSO: TID information to <i>A₄ and A₅ Gain and Phase vs Frequency, A₄ and A₅ Noninverting Closed-Loop Response, A₄ and A₅ Inverting Closed-Loop Response, A₄ and A₅ Capacitive Load Response</i> curves in the <i>Typical Characteristics</i>	10
• Added Part Number flow information table to the <i>Device Nomenclature</i>	30

Changes from Revision A (October 2023) to Revision B (December 2025)	Page
• Added description of device flow information in <i>Specifications</i>	4
• Merged <i>Electrical Characteristics</i> $V_S = \pm 2.25V$ to $\pm 18V$ and <i>Electrical Characteristics</i> $V_S = 5V$ Single Supply into <i>Electrical Characteristics</i>	6
• Changed typical test condition $V_{REF} = 0V$ to $V_{REF} = V_S / 2$ Added <i>all chips site origins (CSO)</i> condition to the typical test conditions in the <i>Electrical Characteristics</i>	6
• Change test condition V_{CM} formula to include V_{REF}	6
• Added different fabrication process specifications for Short-Circuit Current in the <i>Electrical Characteristics</i> ...	6
• Added different fabrication process specifications for Slew Rate in the <i>Electrical Characteristics</i>	6
• Added different fabrication process specifications for Overload Recovery in the <i>Electrical Characteristics</i>	6
• Added different fabrication process specifications for Quiescent Current in the <i>Electrical Characteristics</i>	6
• Added <i>all chips site origins (CSO)</i> condition to the typical test conditions in the <i>Typical Characteristics</i>	9
• Added CSO: SHE information to <i>Common-mode Rejection vs Frequency</i> , <i>Power Supply Rejection vs Frequency</i> , <i>Quiescent Current vs Temperature</i> and <i>Maximum Output Voltage Swing vs Output Current</i> curves in the <i>Typical Characteristics</i>	9
• Added <i>Slew Rate vs Temperature</i> and <i>Large-signal Step Response</i> ($G = 1$, $R_L = 10k\Omega$, $C_L = 200pF$ curves for CSO: SHE flow in the <i>Typical Characteristics</i>	9
• Added CSO: TID information to <i>Slew Rate vs Temperature</i> and <i>Large-signal Step Response</i> ($G = 1$, $R_L = 10k\Omega$, $C_L = 200pF$ curves in the <i>Typical Characteristics</i>	9
• Added <i>Common-mode Rejection vs Frequency</i> , <i>Power Supply Rejection vs Frequency</i> , <i>Output Voltage Swing vs Output Current (Sourcing)</i> , and <i>Output Voltage Swing vs Output Current (Sinking)</i> curves for CSO: TID in the <i>Typical Characteristics</i>	9
• Added Part Number flow information table to the <i>Device Nomenclature</i>	19

Changes from Revision C (December 2021) to Revision D (December 2025)	Page
• Added description of device flow information in the <i>Specifications</i>	5
• Added <i>all chips site origins (CSO)</i> condition to the typical test conditions in the <i>Electrical Characteristics</i>	7
• Added different fabrication process specifications for Input Impedance in the <i>Electrical Characteristics</i>	7
• Added different fabrication process specifications for Voltage Noise in the <i>Electrical Characteristics</i>	7
• Added different fabrication process specifications for Bandwidth, $-3dB$ in the <i>Electrical Characteristics</i>	7
• Added <i>all chips site origins (CSO)</i> condition to the typical test conditions in the <i>Typical Characteristics</i>	9
• Added CSO: SHE flow information to <i>Gain vs Frequency</i> , <i>Input-Referred Offset Voltage Warmup</i> , and <i>Total Harmonic Distortion + Noise Frequency</i> curves in the <i>Typical Characteristics</i>	9
• Added <i>Input-Referred Noise vs Frequency</i> curve for CSO: SHE flow in the <i>Typical Characteristics</i>	9
• Added CSO: TID flow information to <i>Input-Referred Noise vs Frequency</i> curve in the <i>Typical Characteristics</i>	9
• Added <i>Gain vs Frequency</i> , <i>Input-Referred Offset Voltage Warmup</i> , and <i>Total Harmonic Distortion + Noise Frequency</i> curves for CSO: TID flow in the <i>Typical Characteristics</i>	9
• Added part number flow information table to the <i>Device Nomenclature</i>	21

Changes from Revision A (December 2024) to Revision B (December 2025)	Page
• Added description of device flow information in <i>Specifications</i>	4
• Added <i>all chips site origins (CSO)</i> condition to the typical test conditions in the <i>Electrical Characteristics</i>	6
• Changed current noise from 2pApp to 5pApp in the <i>Electrical Characteristics</i>	6
• Added different fabrication process specs for Short-Circuit Current in the <i>Electrical Characteristics</i>	6
• Added different fabrication process specs for Slew Rate (Rising) in the <i>Electrical Characteristics</i>	6
• Added <i>all chips site origins (CSO)</i> condition to the typical test conditions in the <i>Typical Characteristics</i>	8
• Added CSO: SHE flow information to <i>Output Voltage Swing vs Output Current</i> and <i>Large-Signal Step Response G = 5</i> curves in the <i>Typical Characteristics</i>	8
• Added <i>Output Voltage Swing vs Output Current (Sourcing)</i> , <i>Output Voltage Swing vs Output Current (Sinking)</i> , and <i>Large-Signal Step Response G = 5</i> curves for CSO: TID flow in the <i>Typical Characteristics</i>	8
• Updated common-mode range calculations in the <i>Detailed Design Procedure</i>	18
• Added part number flow information table to the <i>Device Nomenclature</i>	22

The datasheet number will be changing.

Device Family	Change From:	Change To:
LOG114	SBOS301B	SBOS301C
INA146	SBOS109A	SBOS109B
INAx126	SBOS062C	SBOS062D
INA122	SBOS069A	SBOS069B

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/LOG114>

<http://www.ti.com/product/INA146>

<http://www.ti.com/product/INA126>

<http://www.ti.com/product/INA122>

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact.

Changes to product identification resulting from this PCN:

None.

Product Affected:

LOG114AIRGVR	LOG114AIRGVR.A	LOG114AIRGVR.B	LOG114AIRGVT
LOG114AIRGVT.A	LOG114AIRGVT.B	INA146UA/2K5	INA146UA/2K5.B
INA126U	INA126U/2K5	INA2126E/250	INA2126EA/250
INA126U/2K5G4.B	INA2126EA/250.B	INA2126U.B	INA2126EA/2K5
INA126UA/2K5	INA2126UA/2K5.B	INA2126UA/2K5	INA2126UG4.B
INA126EA/250	INA126E/250.B	INA126E/250	INA126EA/2K5
INA126EA/250.B	INA126E/2K5.B	INA126E/2K5G4	INA126U/2K5.B
INA126EA/2K5.B	INA2126E/250.B	INA2126EA/2K5.B	INA126UA

INA2126U	INA126E/2K5	INA2126UA	INA126UA/2K5.B
INA2126UA.B	INA126U/2K5G4	INA126U.B	INA2126E/2K5
INA126EA/2K51G4	INA126UA.B	INA2126E/2K5.B	INA2126UG4
INA122P	INA122P.A	INA122PA	INA122PA.A
INA122PAG4	INA122U/2K5	INA122U/2K5.A	INA122U/2K5.B
INA122UA/2K5	INA122UA/2K5.A	INA122UA/2K5.B	

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI’s products are provided subject to TI’s Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI’s provision of these resources does not expand or otherwise alter TI’s applicable warranties or warranty disclaimers for TI products.